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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	Z8
Core Size	8-Bit
Speed	16MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	24
Program Memory Size	4KB (4K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	237 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	28-LCC (J-Lead)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z86e3016veg

Power connections follow conventional descriptions below:

Connection	Circuit	Device
Power	V_{CC}	V_{DD}
Ground	GND	V_{SS}

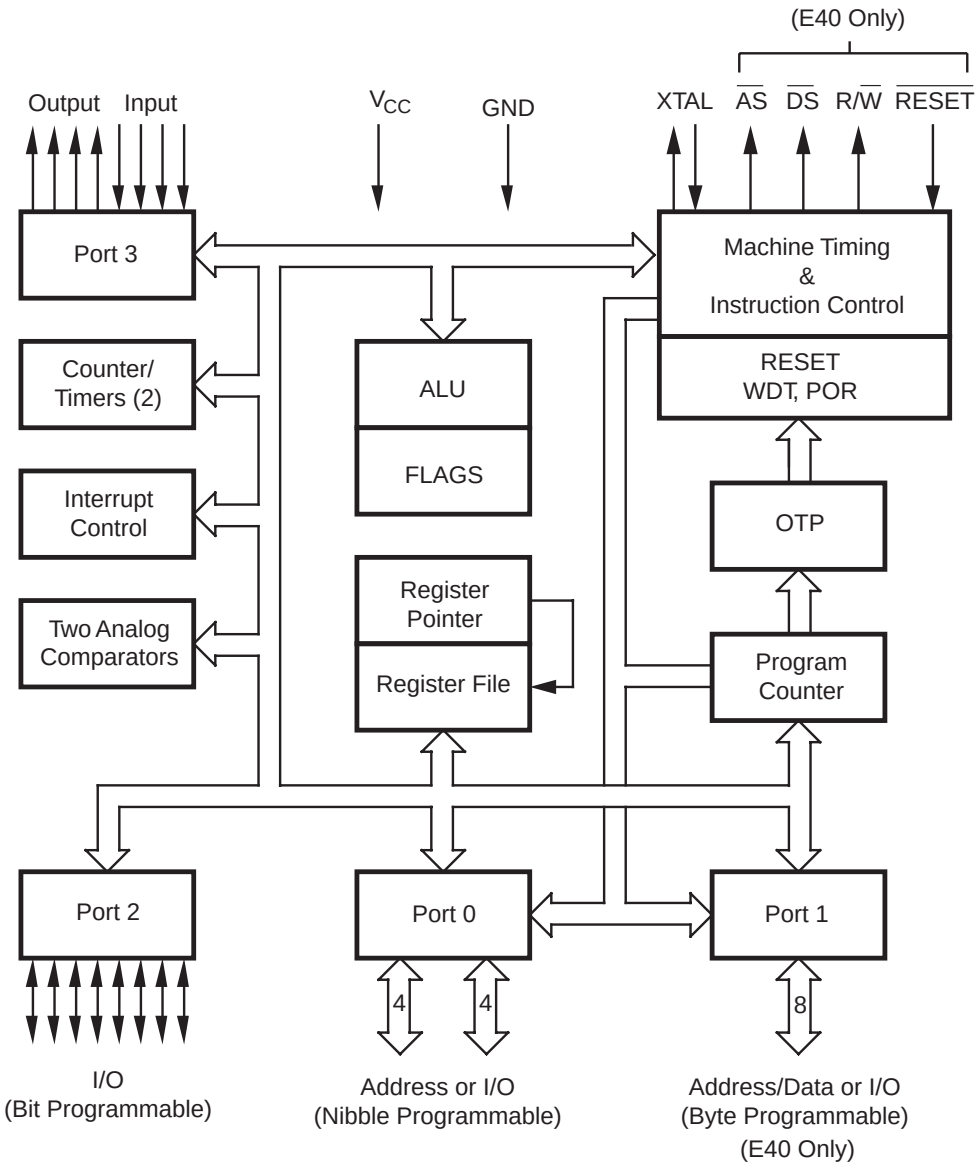


Figure 1. Z86E30/E31/E40 Functional Block Diagram

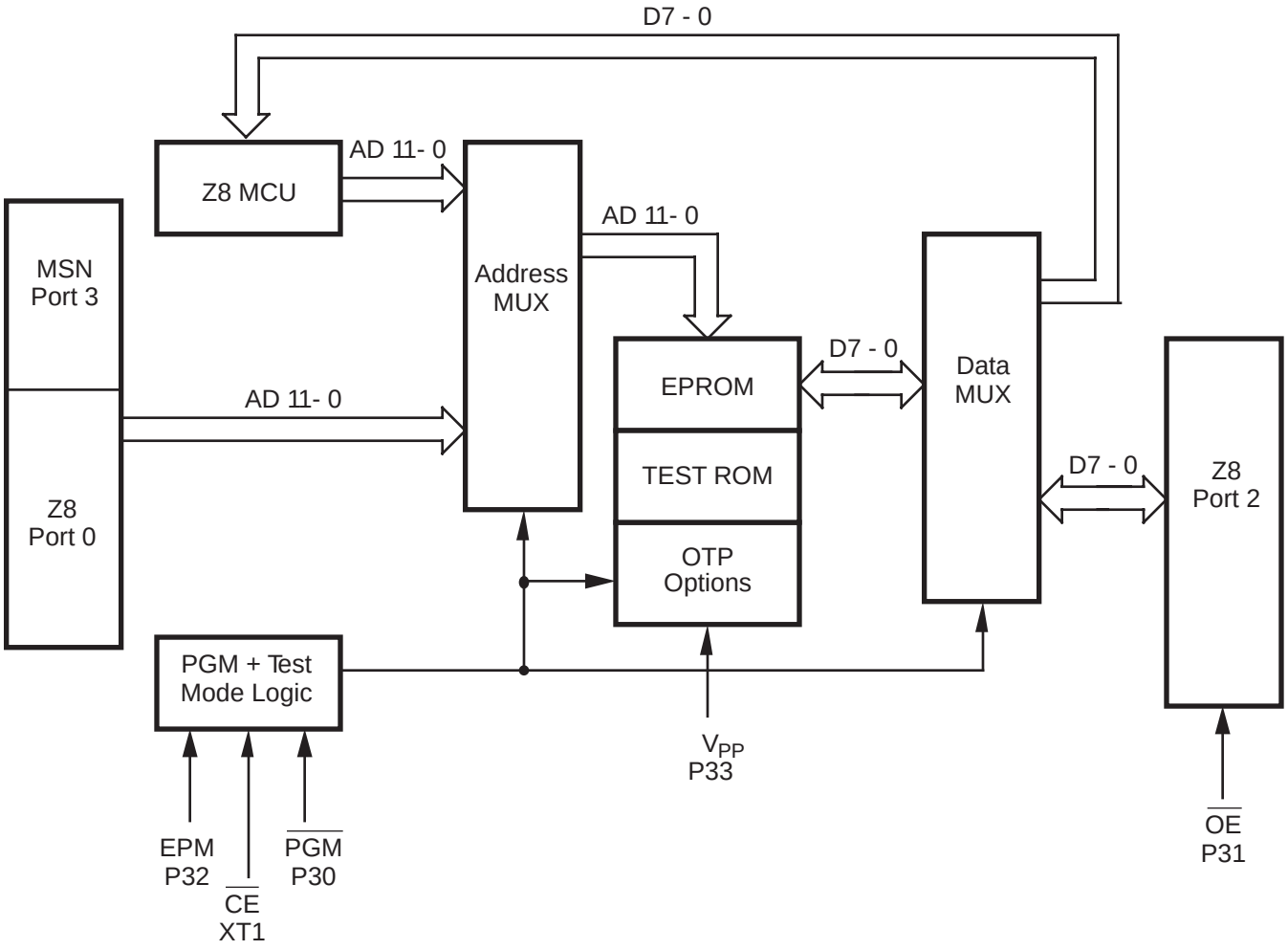


Figure 2. EPROM Programming Block Diagram

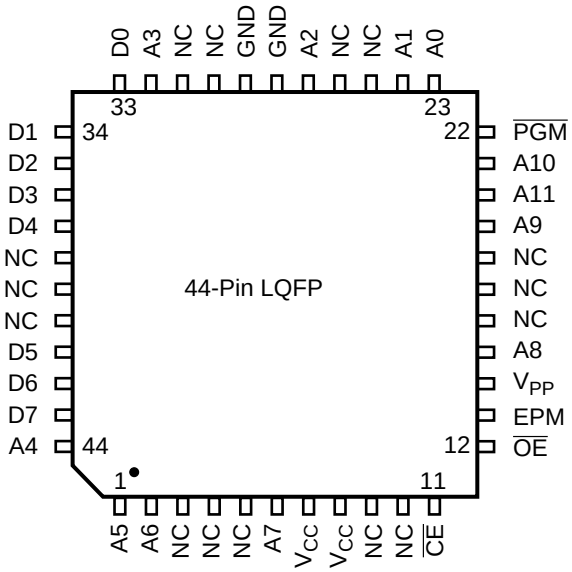


Figure 8. 44-Pin LQFP Pin Configuration EPROM Programming Mode

Table 6. 44-Pin LQFP Pin Configuration EPROM Programming Mode

Pin #	Symbol	Function	Direction
1–2	A5–A6	Address 5,6	Input
3–4	NC	No Connection	
5	A7	Address 7	Input
6–7	V_{CC}	Power Supply	
8–10	NC	No Connection	
11	$\overline{CE}$	Chip Select	Input
12	$\overline{OE}$	Output Enable	Input
13	EPM	EPROM Prog. Mode	Input
14	V_{PP}	Prog. Voltage	Input
15	A8	Address 8	Input
16–18	NC	No Connection	
19	A9	Address 9	Input
20	A11	Address 11	Input
21	A10	Address 10	Input
22	$\overline{PGM}$	Prog. Mode	Input

Table 6. 44-Pin LQFP Pin Configuration EPROM Programming Mode

Pin #	Symbol	Function	Direction
23–24	A0,A1	Address 0,1	Input
25–26	NC	No Connection	
27	A2	Address 2	Input
28–29	GND	Ground	
30–31	NC	No Connection	
32	A3	Address 3	Input
33–37	D0–D4	Data 0,1,2,3,4	In/Output
38–40	NC	No Connection	
41–43	D5–D7	Data 5,6,7	In/Output
44	A4	Address 4	Input

DC ELECTRICAL CHARACTERISTICS (Continued)

			T_A=–40 °C to +105 °C					
Sym	Parameter	V_{CC} Note [3]	Min	Max	Typical @ 25°C	Units	Conditions	Notes
I_{ALH}	Auto Latch High Current	4.5V	-1.0	-10	-3.8	µA	$0V < V_{IN} < V_{CC}$	9
		5.5V	-1.0	-10	-3.8	µA	$0V < V_{IN} < V_{CC}$	9
T_{POR}	Power On Reset	4.5V	2.0	14	4	mS		
		5.5V	2.0	14	4	mS		
V_{LV}	Auto Reset Voltage		2.0	3.3	2.9	V		1

1. Device does function down to the Auto Reset voltage.
2. GND=0V
3. The V_{CC} voltage specification of 5.5V guarantees 5.0V ± 0.5V.
4. All outputs unloaded, I/O pins floating, inputs at rail.
5. CL1= CL2 = 22 pF
6. Same as note [4] except inputs at V_{CC}.
7. Maximum temperature is 70°C
8. STD Mode (not Low EMI Mode)
9. Auto Latch (mask option) selected
10. For analog comparator inputs when analog comparators are enabled.
11. Clock must be forced Low, when XTAL1 is clock driven and XTAL2 is floating.
12. Typicals are at V_{CC} = 5.0V
13. Z86E40 only
14. WDT is not running.

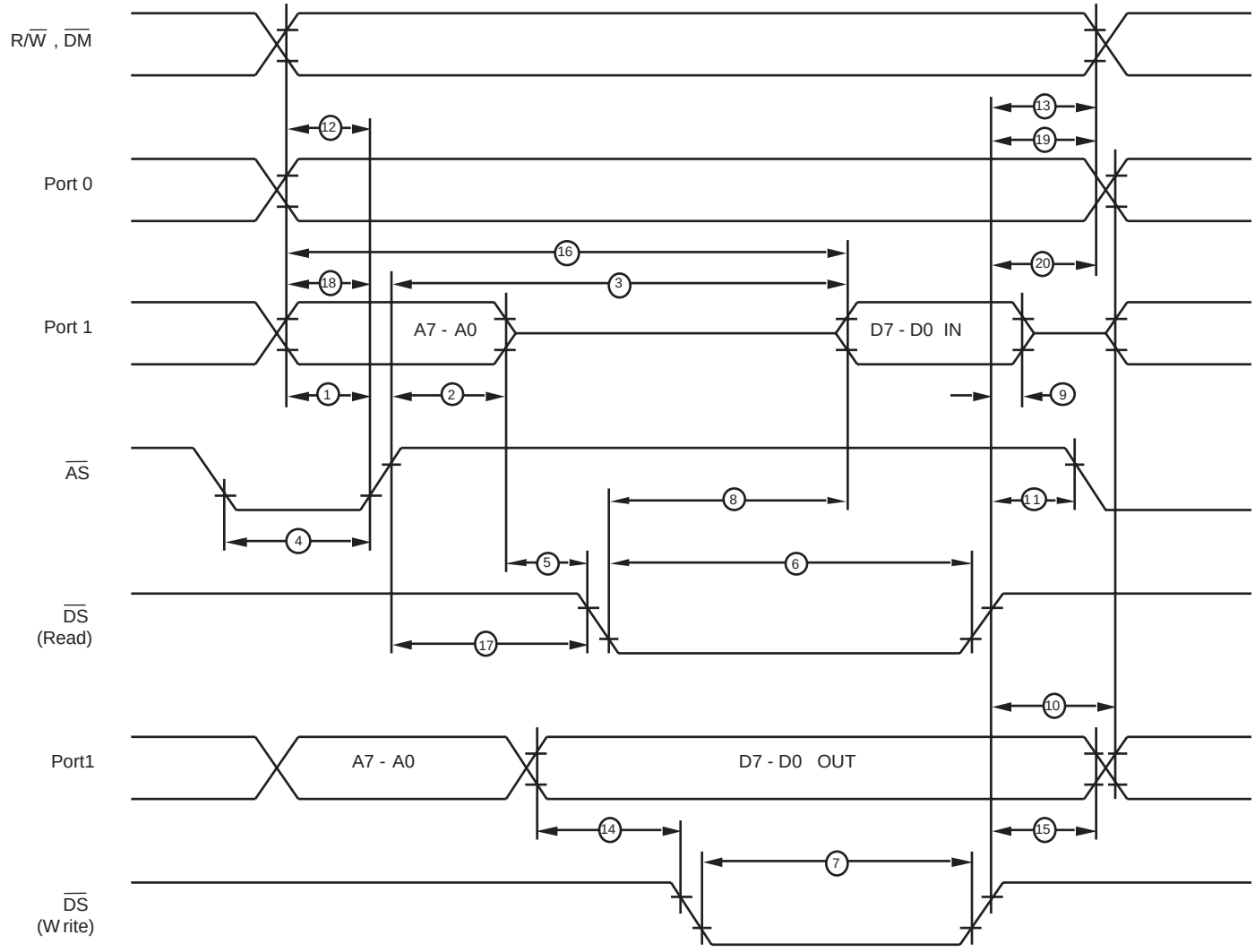


Figure 14. External I/O or Memory Read/Write Timing
Z86E40 Only

Additional Timing Table (Divide-By-One Mode)

				T_A = 0 °C to +70 °C		T_A = -40 °C to +105 °C			
				4 MHz		4 MHz			
No	Symbol	Parameter	V_{CC} Note [6]	Min	Max	Min	Max	Units	Notes
1	TpC	Input Clock Period	3.5V	250	DC	250	DC	ns	1,7,8
			5.5V	250	DC	250	DC	ns	1,7,8
2	TrC,TfC	Clock Input Rise & Fall Times	3.5V		25		25	ns	1,7,8
			5.5V		25		25	ns	1,7,8
3	TwC	Input Clock Width	3.5V	100		100		ns	1,7,8
			5.5V	100		100		ns	1,7,8
4	TwTinL	Timer Input Low Width	3.5V	100		100		ns	1,7,8
			5.5V	70		70		ns	1,7,8
5	TwTinH	Timer Input High Width	3.5V	5TpC		5TpC			1,7,8
			5.5V	5TpC		5TpC			1,7,8
6	TpTin	Timer Input Period	3.5V	8TpC		8TpC			1,7,8
			5.5V	8TpC		8TpC			1,7,8
7	TrTin, TfTin	Timer Input Rise & Fall Timer	3.5V		100		100	ns	1,7,8
			5.5V		100		100	ns	1,7,8
8A	TwIL	Int. Request Low Time	3.5V	100		100		ns	1,2,7,8
			5.5V	70		70		ns	1,2,7,8
8B	TwIL	Int. Request Low Time	3.5V	5TpC		5TpC			1,3,7,8
			5.5V	5TpC		5TpC			1,3,7,8
9	TwIH	Int. Request Input High Time	3.5V	5TpC		5TpC			1,2,7,8
			5.5V	5TpC		5TpC			1,2,7,8
10	Twsm	STOP Mode Recovery Width Spec	3.5V	12		12		ns	4,8
			5.5V	12		12		ns	4,8
11	Tost	Oscillator Startup Time	3.5V		5TpC		5TpC		4,8,9
			5.5V		5TpC				

Notes:

1. Timing Reference uses 0.7 V_{CC} for a logic 1 and 0.2 V_{CC} for a logic 0.
2. Interrupt request via Port 3 (P31–P33).
3. Interrupt request via Port 3 (P30).
4. SMR-D5 = 1, POR STOP Mode Delay is on.
5. Reg. WDTMR.
6. The V_{CC} voltage specification of 5.5V guarantees 5.0V ± 0.5V and the V_{CC} voltage specification of 3.5V guarantees 3.5V only.
7. SMR D1 = 0.
8. Maximum frequency for internal system clock is 4 MHz when using XTAL divide-by-one mode.
9. For RC and LC oscillator, and for oscillator driven by clock driver.

PIN FUNCTIONS

EPROM Programming Mode

D7–D0 Data Bus. The data can be read from or written to external memory through the data bus.

A11–A0 Address Bus. During programming, the EPROM address is written to the address bus.

V_{CC} Power Supply. This pin must supply 5V during the EPROM read mode and 6V during other modes.

$\overline{CE}$ Chip Enable (active Low). This pin is active during EPROM Read Mode, Program Mode, and Program Verify Mode.

$\overline{OE}$ Output Enable (active Low). This pin drives the direction of the Data Bus. When this pin is Low, the Data Bus is output, when High, the Data Bus is input.

EPM EPROM Program Mode. This pin controls the different EPROM Program Mode by applying different voltages.

V_{PP} Program Voltage. This pin supplies the program voltage.

$\overline{PGM}$ Program Mode (active Low). When this pin is Low, the data is programmed to the EPROM through the Data Bus.

Application Precaution

The production test-mode environment may be enabled accidentally during normal operation if excessive noise surges above V_{CC} occur on pins XTAL1 and $\overline{RESET}$.

In addition, processor operation of Z8 OTP devices may be affected by excessive noise surges on the V_{PP}, $\overline{CE}$, $\overline{EPM}$, $\overline{OE}$ pins while the microcontroller is in Standard Mode.

Recommendations for dampening voltage surges in both test and OTP mode include the following:

- Using a clamping diode to V_{CC}
- Adding a capacitor to the affected pin

Standard Mode

XTAL Crystal 1 (time-based input). This pin connects a parallel-resonant crystal, ceramic resonator, LC, RC network, or external single-phase clock to the on-chip oscillator input.

XTAL2 Crystal 2 (time-based output). This pin connects a parallel-resonant crystal, ceramic resonator, LC, or RC network to the on-chip oscillator output.

R/$\overline{W}$ Read/Write (output, write Low). The R/$\overline{W}$ signal is Low when the CCP is writing to the external program or data memory (Z86E40 only).

$\overline{RESET}$ Reset (input, active Low). Reset will initialize the MCU. Reset is accomplished either through Power-On, Watch-Dog Timer reset, STOP-Mode Recovery, or external reset. During Power-On Reset and Watch-Dog Timer Reset, the internally generated reset drives the reset pin low for the POR time. Any devices driving the reset line must be open-drain in order to avoid damage from a possible conflict during reset conditions. Pull-up is provided internally. After the POR time, $\overline{RESET}$ is a Schmitt-triggered input.

To avoid asynchronous and noisy reset problems, the Z86E40 is equipped with a reset filter of four external clocks (4TpC). If the external reset signal is less than 4TpC in duration, no reset occurs. On the fifth clock after the reset is detected, an internal RST signal is latched and held for an internal register count of 18 external clocks, or for the duration of the external reset, whichever is longer. During the reset cycle, $\overline{DS}$ is held active Low while $\overline{AS}$ cycles at a rate of TpC/2. Program execution begins at location 000CH, 5–10 TpC cycles after $\overline{RESET}$ is released. For Power-On Reset, the reset output time is 5 ms. The Z86E40 does not reset WDTMR, SMR, P2M, and P3M registers on a STOP-Mode Recovery operation.

$\overline{ROMless}$ (input, active Low). This pin, when connected to GND, disables the internal ROM and forces the device to function as a Z86C90/C89 ROMless Z8. (Note that, when left unconnected or pulled High to V_{CC}, the device functions normally as a Z8 ROM version).

Note: When using in ROM Mode in High EMI (noisy) environment, the ROMless pins should be connected directly to V_{CC}.

Port 0 (P07–P00). Port 0 is an 8-bit, bidirectional, CMOS-compatible I/O port. These eight I/O lines can be configured under software control as a nibble I/O port, or as an address port for interfacing external memory. The input buffers are Schmitt-triggered and nibble programmed. Either nibble output that can be globally programmed as push-pull or open-drain. Low EMI output buffers can be globally programmed by the software. Port 0 can be placed under handshake control. In Handshake Mode, Port 3 lines P32 and P35 are used as handshake control lines. The handshake direction is determined by the configuration (input or output) assigned to Port 0's upper nibble. The lower nibble must have the same direction as the upper nibble.

For external memory references, Port 0 provides address bits A11–A8 (lower nibble) or A15–A8 (lower and upper nibble) depending on the required address space. If the address range requires 12 bits or less, the upper nibble of Port 0 can be programmed independently as I/O while the lower nibble is used for addressing. If one or both nibbles are needed for I/O operation, they must be configured by writing to the Port 0 mode register. In ROMless mode, after a hardware reset, Port 0 is configured as address lines A15–A8, and extended timing is set to accommodate slow memory access. The initialization routine can include reconfiguration to eliminate this extended timing mode. In ROM mode, Port 0 is defined as input after reset.

Port 0 can be set in the High-Impedance Mode if selected as an address output state, along with Port 1 and the control signals $\overline{AS}$, $\overline{DS}$, and R/$\overline{W}$ (Figure 18).

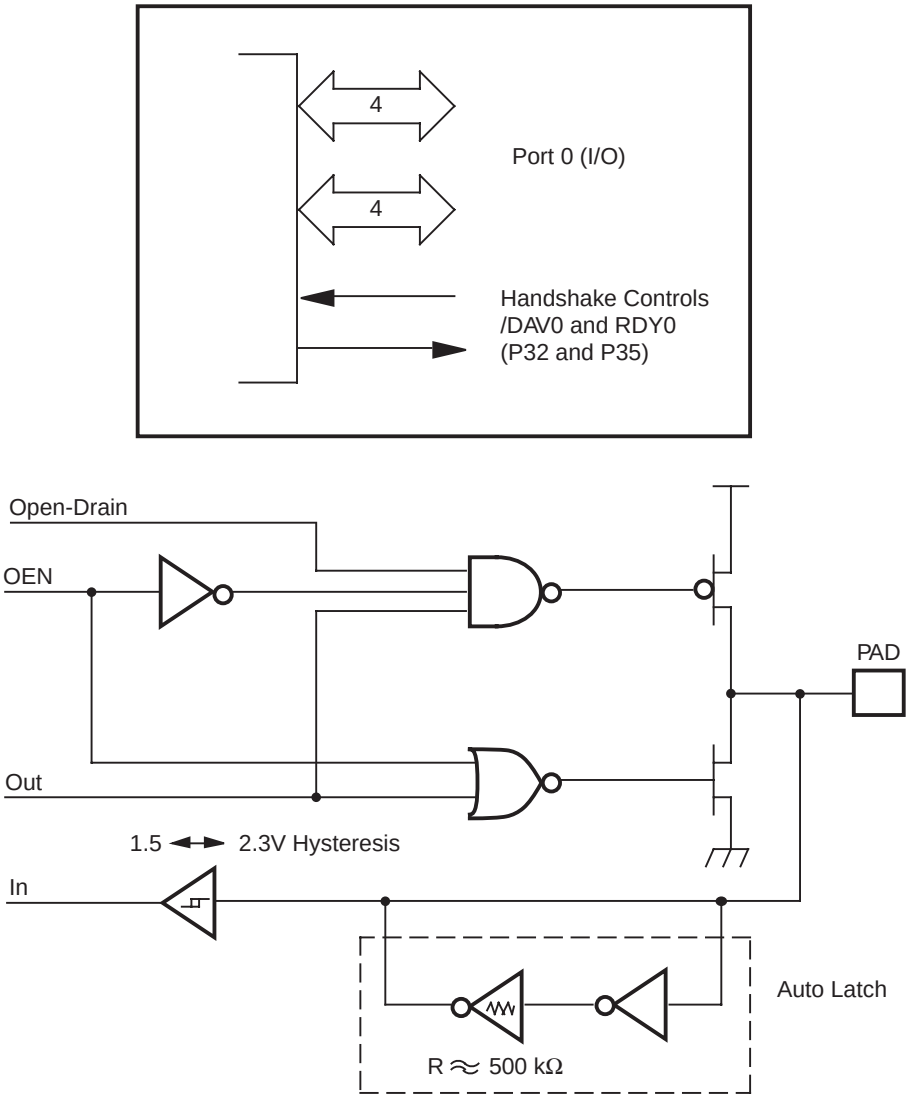


Figure 18. Port 0 Configuration

Port 2 (P27–P20). Port 2 is an 8-bit, bidirectional, CMOS-compatible I/O port. These eight I/O lines can be configured under software control as an input or output, independently. All input buffers are Schmitt-triggered. Bits programmed as outputs can be globally programmed as either push-pull or open-drain. Low EMI output buffers can be globally programmed by the software. When used as an I/O port, Port 2 can be placed under handshake control.

In Handshake Mode, Port 3 lines P31 and P36 are used as handshake control lines. The handshake direction is determined by the configuration (input or output) assigned to bit 7 of Port 2 (Figure 20).

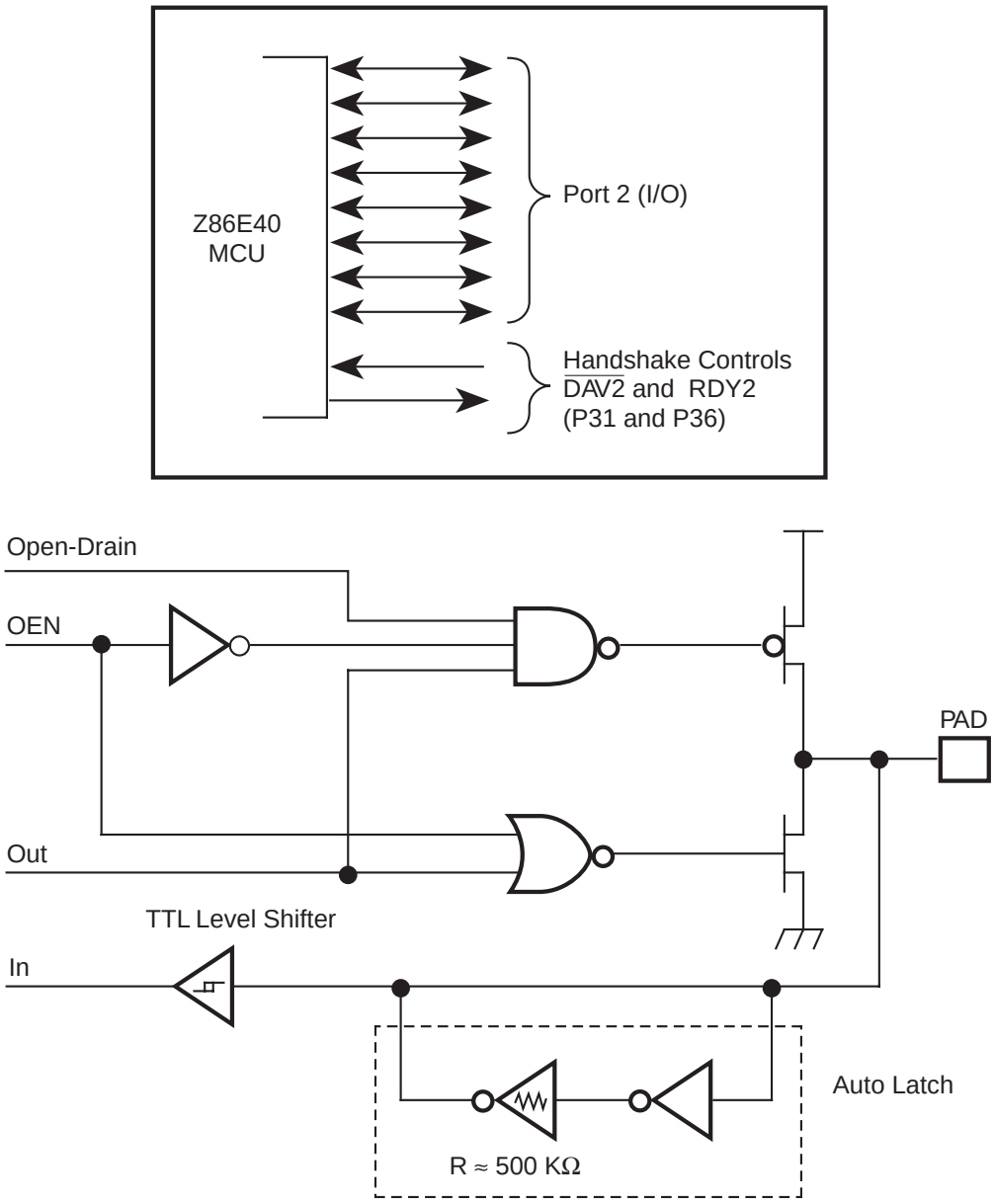


Figure 20. Port 2 Configuration

PIN FUNCTIONS (Continued)

Comparator Inputs. Port 3, P31, and P32, each have a comparator front end. The comparator reference voltage P33 is common to both comparators. In analog mode, P31 and P32 are the positive input of the comparators and P33 is the reference voltage of the comparators.

Auto Latch. The Auto Latch puts valid CMOS levels on all CMOS inputs (except P33–P31) that are not externally driven. Whether this level is 0 or 1, cannot be determined. A valid CMOS level, rather than a floating node, reduces excessive supply current flow in the input buffer. Auto Latches are available on Port 0, Port 2, and P30. There are no Auto Latches on P31, P32, and P33.

Low EMI Emission. The Z86E40 can be programmed to operate in a low EMI Emission Mode in the PCON register. The oscillator and all I/O ports can be programmed as low EMI emission mode independently. Use of this feature results in:

- The pre-drivers slew rate reduced to 10 ns typical.
- Low EMI output drivers have resistance of 200 Ohms (typical).
- Low EMI Oscillator.
- Internal SCLK/TCLK= XTAL operation limited to a maximum of 4 MHz – 250 ns cycle time, when Low EMI Oscillator is selected and system clock (SCLK = XTAL, SMR Reg. Bit D1 =1).
- **Note for emulation only:**
  Do not set the emulator to emulate Port 1 in low EMI mode. Port 1 must always be configured in Standard Mode.

FUNCTIONAL DESCRIPTION

The MCU incorporates the following special functions to enhance the standard Z8 architecture to provide the user with increased design flexibility.

RESET. The device is reset in one of three ways:

1. Power-On Reset
2. Watch-Dog Timer
3. STOP-Mode Recovery Source

Note: Having the Auto Power-On Reset circuitry built-in, the MCU does not need to be connected to an external power-on reset circuit. The reset time is 5 ms (typical). The MCU does not reinitialize WDTMR, SMR, P2M, and P3M registers to their reset values on a STOP-Mode Recovery operation.

Note: The device V_{CC} must rise up to the operating V_{CC} specification before the TPOR expires.

Program Memory. The MCU can address up to 4 KB of Internal Program Memory (Figure 22). The first 12 bytes of program memory are reserved for the interrupt vectors. These locations contain six 16-bit vectors that correspond to the six available interrupts. For EPROM mode, byte 12 (000CH) to address 4095 (0FFFH) consists of programmable EPROM. After reset, the program counter points at the address 000CH, which is the starting address of the user program.

In ROMless mode, the Z86E40 can address up to 64 KB of External Program Memory. The ROM/ROMless option is only available on the 44-pin devices.

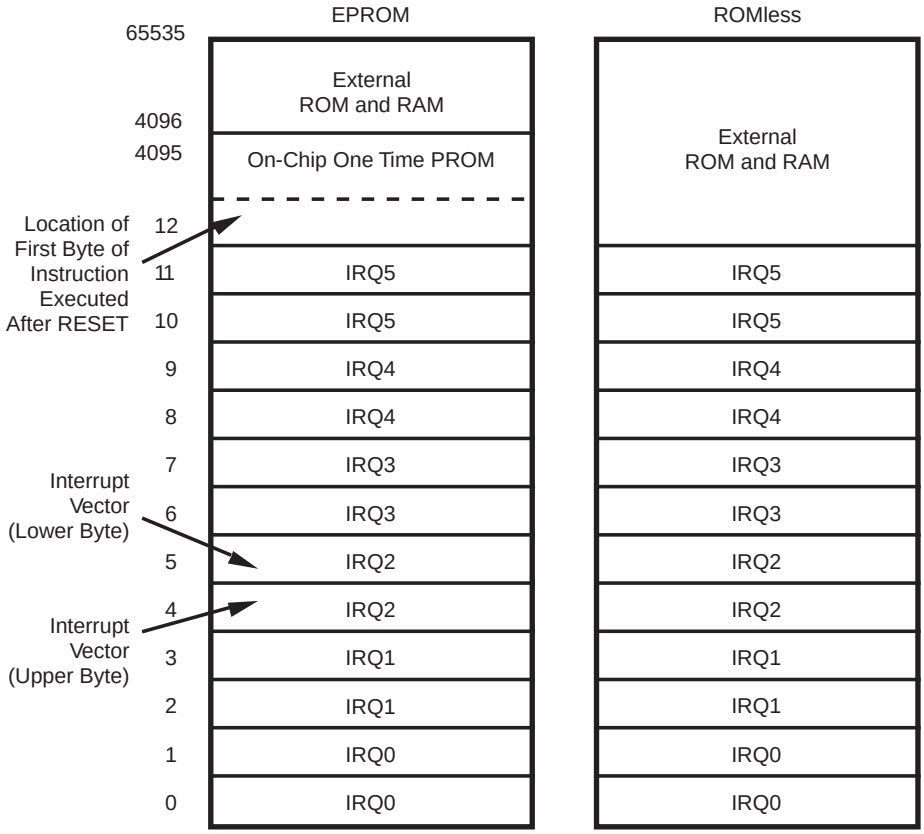


Figure 22. Program Memory Map (ROMless Z86E40 Only)

EPROM Protect. When in ROM Protect Mode, and executing out of External Program Memory, instructions LDC, LDCI, LDE, and LDEI cannot read Internal Program Memory.

When in ROM Protect Mode and executing out of Internal Program Memory, instructions LDC, LDCI, LDE, and LDEI can read Internal Program Memory.

FUNCTIONAL DESCRIPTION (Continued)

Interrupts. The MCU has six different interrupts from six different sources. The interrupts are maskable and prioritized (Figure 28). The six sources are divided as follows: four sources are claimed by Port 3 lines P33–P30) and two in counter/timers. The Interrupt Mask Register globally or individually enables or disables the six interrupt requests (Table 10).

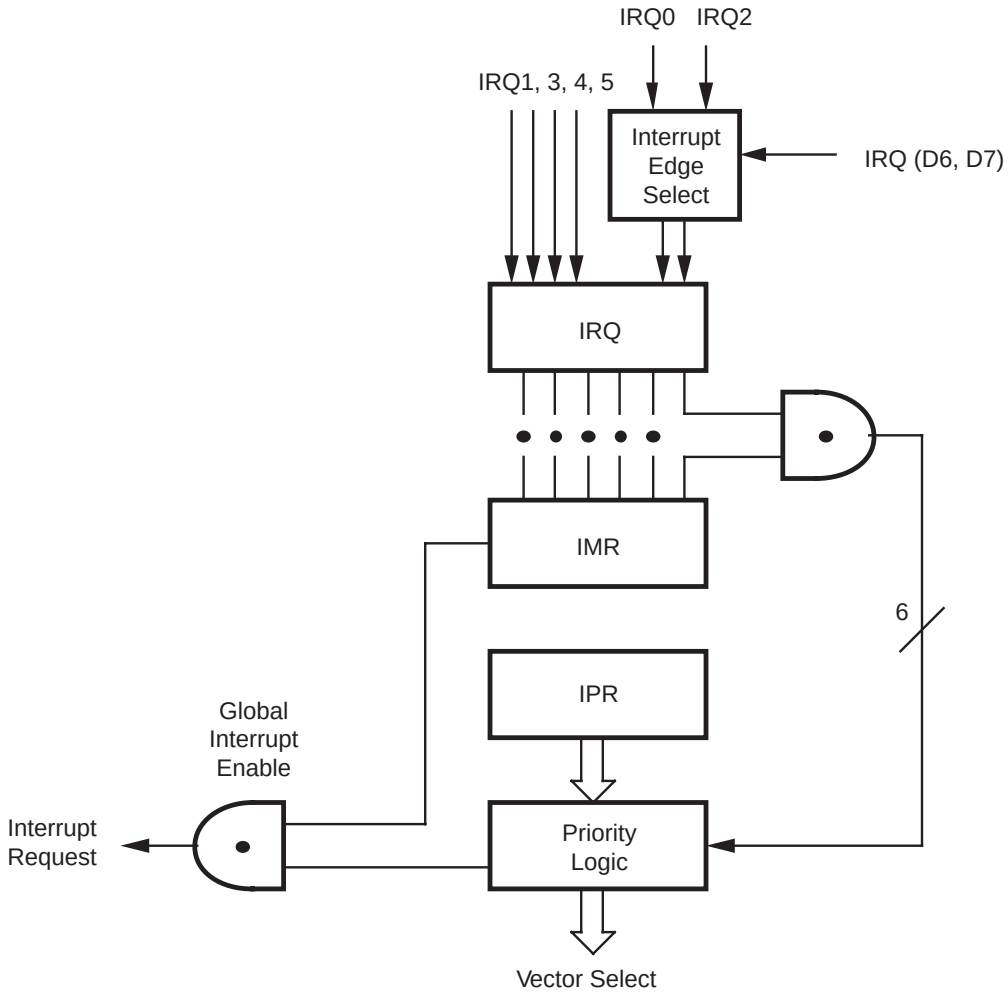


Figure 28. Interrupt Block Diagram

Table 10. Interrupt Types, Sources, and Vectors

Name	Source	Vector Location	Comments
IRQ0	$\overline{DAV0}$, IRQ0	0, 1	External (P32), Rising/Falling Edge Triggered
IRQ1	IRQ1	2, 3	External (P33), Falling Edge Triggered
IRQ2	$\overline{DAV2}$, IRQ2, T_{IN}	4, 5	External (P31), Rising/Falling Edge Triggered
IRQ3	IRQ3	6, 7	External (P30), Falling Edge Triggered
IRQ4	T0	8, 9	Internal
IRQ5	TI	10, 11	Internal

FUNCTIONAL DESCRIPTION (Continued)

Power-On Reset (POR). A timer circuit clocked by a dedicated on-board RC oscillator is used for the Power-On Reset (POR) timer function. The POR timer allows V_{CC} and the oscillator circuit to stabilize before instruction execution begins.

The POR timer circuit is a one-shot timer triggered by one of three conditions:

1. Power fail to Power OK status
2. Stop-Mode Recovery (if D5 of SMR=0)
3. WDT time-out

The POR time is a nominal 5 ms. Bit 5 of the STOP mode Register (SMR) determines whether the POR timer is bypassed after STOP-Mode Recovery (typical for an external clock and RC/LC oscillators with fast start up times).

HALT. Turns off the internal CPU clock, but not the XTAL oscillation. The counter/timers and external interrupt IRQ0, IRQ1, and IRQ2 remain active. The device is recovered by interrupts, either externally or internally generated. An interrupt request must be executed (enabled) to exit HALT Mode. After the interrupt service routine, the program continues from the instruction after the HALT.

In order to enter STOP or HALT Mode, it is necessary to first flush the instruction pipeline to avoid suspending execution in mid-instruction. To do this, the user must execute a NOP (Opcode=FFH) immediately before the appropriate sleep instruction, that is:

```
FF      NOP     ; clear the pipeline
6F      STOP    ; enter STOP Mode
                or
FF      NOP     ; clear the pipeline
7F      HALT    ; enter HALT Mode
```

STOP. This instruction turns off the internal clock and external crystal oscillation and reduces the standby current to 10 microamperes or less. STOP Mode is terminated by one of the following resets: either by WDT time-out, POR, a Stop-Mode Recovery Source, which is defined by the SMR register or external reset. This causes the processor to restart the application program at address 000CH.

Port Configuration Register (PCON). The PCON register configures the ports individually; comparator output on Port 3, open-drain on Port 0 and Port 1, low EMI on Ports 0, 1, 2 and 3, and low EMI oscillator. The PCON register is located in the expanded register file at Bank F, location 00 (Figure 30).

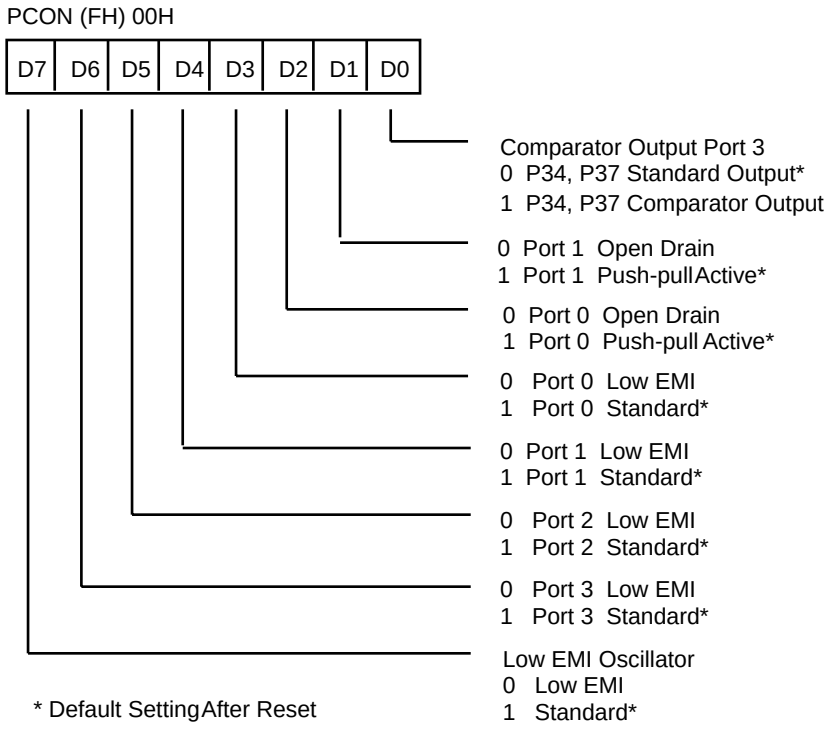


Figure 30. Port Configuration Register (PCON) (Write Only)

Comparator Output Port 3 (D0). Bit 0 controls the comparator output in Port 3. A “1” in this location brings the comparator outputs to P34 and P37, and a “0” releases the Port to its standard I/O configuration. The default value is 0.

Port 1 Open-Drain (D1). Port 1 can be configured as an open-drain by resetting this bit (D1=0) or configured as push-pull active by setting this bit (D1=1). The default value is 1.

Port 0 Open-Drain (D2). Port 0 can be configured as an open-drain by resetting this bit (D2=0) or configured as push-pull active by setting this bit (D2=1). The default value is 1.

Low EMI Port 0 (D3). Port 0 can be configured as a Low EMI Port by resetting this bit (D3=0) or configured as a Standard Port by setting this bit (D3=1). The default value is 1.

Low EMI Port 1 (D4). Port 1 can be configured as a Low EMI Port by resetting this bit (D4=0) or configured as a Standard Port by setting this bit (D4=1). The default value is 1. **Note:** The emulator does not support Port 1 low EMI mode and must be set D4 = 1.

Low EMI Port 2 (D5). Port 2 can be configured as a Low EMI Port by resetting this bit (D5=0) or configured as a Standard Port by setting this bit (D5=1). The default value is 1.

Low EMI Port 3 (D6). Port 3 can be configured as a Low EMI Port by resetting this bit (D6=0) or configured as a Standard Port by setting this bit (D6=1). The default value is 1.

Low EMI OSC (D7). This bit of the PCON Register controls the low EMI noise oscillator. A “1” in this location configures the oscillator with standard drive. While a “0” configures the oscillator with low noise drive, however, it does not affect the relationship of SCLK and XTAL. The low EMI mode will reduce the drive of the oscillator (OSC). The default value is 1. **Note:** 4 MHz is the maximum external clock frequency when running in the low EMI oscillator mode.

Stop-Mode Recovery Register (SMR). This register selects the clock divide value and determines the mode of Stop-Mode Recovery (Figure 31). All bits are Write Only except bit 7 which is a Read Only. Bit 7 is a flag bit that is hardware set on the condition of STOP Recovery and reset by a power-on cycle. Bit 6 controls whether a low or high level is required from the recovery source. Bit 5 controls the reset delay after recovery. Bits 2, 3, and 4 of the SMR register specify the Stop-Mode Recovery Source. The SMR is located in Bank F of the Expanded Register Group at address 0BH.

FUNCTIONAL DESCRIPTION (Continued)

Table 12. Stop-Mode Recovery Source

D4	D3	D2	SMR Source selection
0	0	0	POR recovery only
0	0	1	P30 transition
0	1	0	P31 transition (Not in analog mode)
0	1	1	P32 transition (Not in analog mode)
1	0	0	P33 transition (Not in analog mode)
1	0	1	P27 transition
1	1	0	Logical NOR of Port 2 bits 0–3
1	1	1	Logical NOR of Port 2 bits 0–7

Stop-Mode Recovery Delay Select (D5). The 5 ms RESET delay after Stop-Mode Recovery is disabled by programming this bit to a zero. A “1” in this bit will cause a 5 ms RESET delay after Stop-Mode Recovery. The default condition of this bit is 1. If the fast wake up mode is selected, the Stop-Mode Recovery source needs to be kept active for at least 5TpC.

Stop-Mode Recovery Level Select (D6). A “1” in this bit defines that a high level on any one of the recovery sources wakes the MCU from STOP Mode. A 0 defines low level recovery. The default value is 0.

Cold or Warm Start (D7). This bit is set by the device upon entering STOP Mode. A “0” in this bit indicates that the device has been reset by POR (cold). A “1” in this bit indicates the device was awakened by a SMR source (warm).

Stop-Mode Recovery Register 2 (SMR2). This register contains additional Stop-Mode Recovery sources. When the Stop-Mode Recovery sources are selected in this register then SMR Register. Bits D2, D3, and D4 must be 0.

SMR:10		Operation
D1	**D0**	**Description of Action**
0	0	POR and/or external reset recovery
0	1	Logical AND of P20 through P23
1	0	Logical AND of P20 through P27

Watch-Dog Timer Mode Register (WDTMR). The WDT is a retriggerable one-shot timer that resets the Z8 if it reaches its terminal count. The WDT is disabled after Power-On Reset and initially enabled by executing the WDT instruction and refreshed on subsequent executions of the WDT instruction. The WDT is driven either by an on-board RC oscillator or an external oscillator from XTAL1 pin. The POR clock source is selected with bit 4 of the WDT register.

Note: Execution of the WDT instruction affects the Z (Zero), S (Sign), and V (Overflow) flags.

WDT Time-Out Period (D0 and D1). Bits 0 and 1 control a tap circuit that determines the time-out periods that can be obtained (Table 13). The default value of D0 and D1 are 1 and 0, respectively.

Table 13. Time-out Period of WDT

D1	D0	Time-out of the Internal RC OSC	Time-out of the System Clock
0	0	5 ms	128 SCLK
0	1	10 ms*	256 SCLK*
1	0	20 ms	512 SCLK
1	1	80 ms	2048 SCLK

Notes:
*The default setting is 10 ms.

WDT During HALT Mode (D2). This bit determines whether or not the WDT is active during HALT Mode. A “1” indicates that the WDT is active during HALT. A “0” disables the WDT in HALT Mode. The default value is “1”.

WDT During STOP Mode (D3). This bit determines whether or not the WDT is active during STOP mode. A “1” indicates active during STOP. A “0” disables the WDT during STOP Mode. This is applicable only when the WDT clock source is the internal RC oscillator.

Clock Source For WDT (D4). This bit determines which oscillator source is used to clock the internal POR and WDT counter chain. If the bit is a 1, the internal RC oscillator is bypassed and the POR and WDT clock source is driven from the external pin, XTAL1, and the WDT is stopped in STOP Mode. The default configuration of this bit is 0, which selects the RC oscillator.

Permanent WDT. When this feature is enabled, the WDT is enabled after reset and will operate in Run and Halt Mode. The control bits in the WDTMR do not affect the WDT operation. If the clock source of the WDT is the internal RC oscillator, then the WDT will run in STOP mode. If the clock source of the WDT is the XTAL1 pin, then the WDT will not run in STOP mode.

Note: WDT time-out in STOP Mode will not reset SMR,SMR2,PCON, WDTMR, P2M, P3M, Ports 2 & 3 Data Registers.

WDTMR Register Accessibility. The WDTMR register is accessible only during the **first 60** internal system clock

Z86E40 TIMING DIAGRAMS

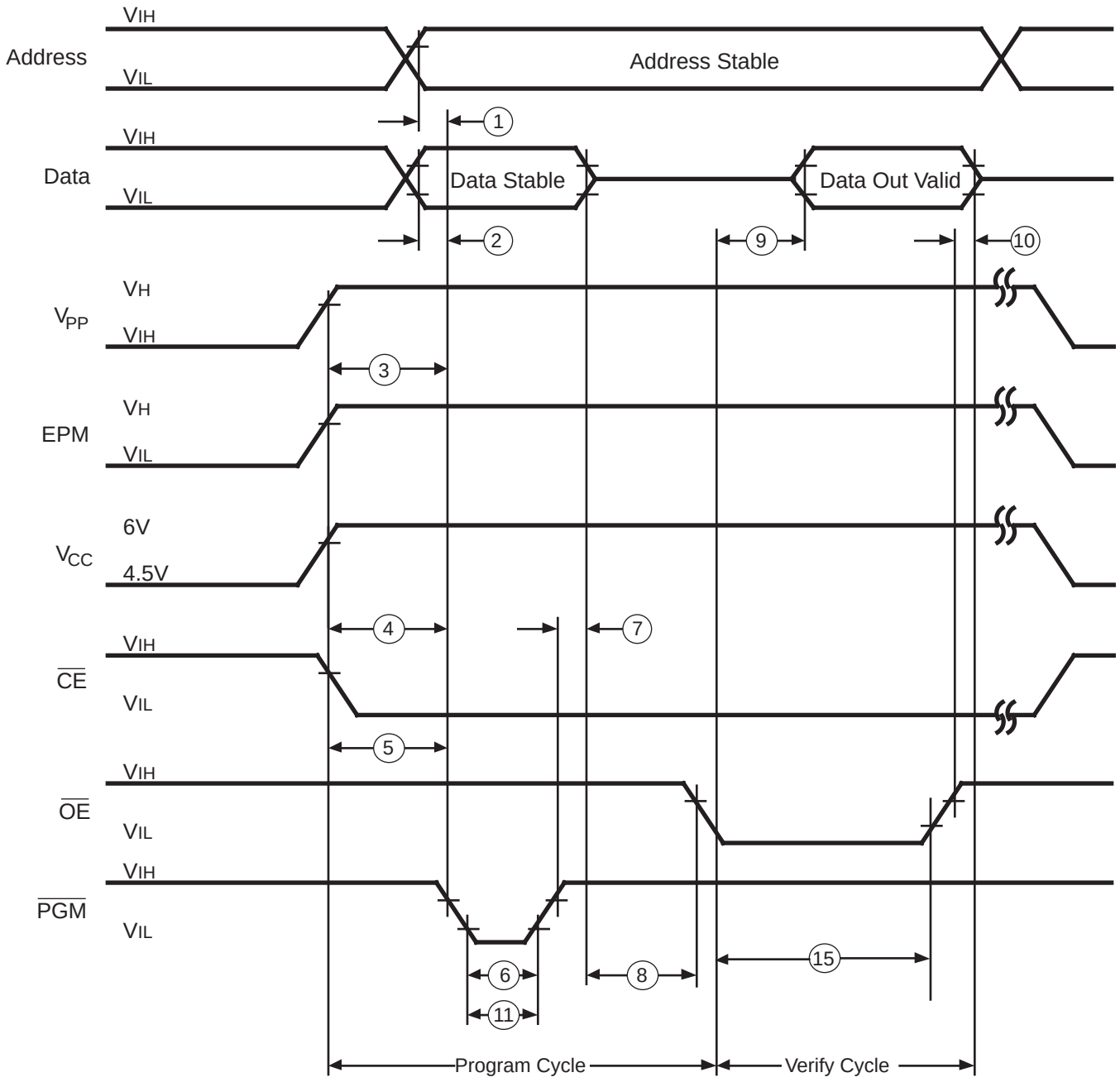


Figure 37. Timing Diagram of EPROM Program and Verify Modes

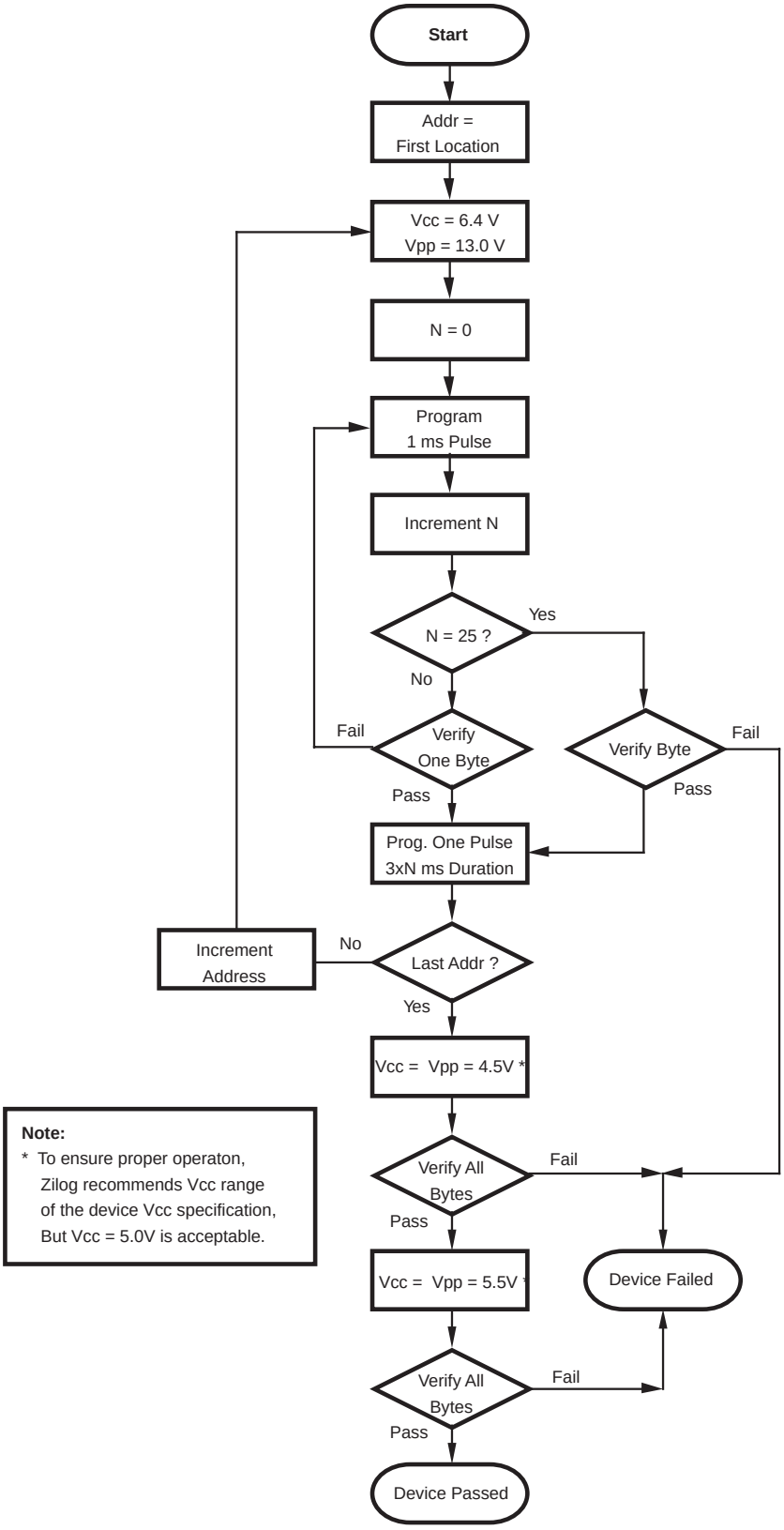


Figure 40. Z86E40 Programming Algorithm

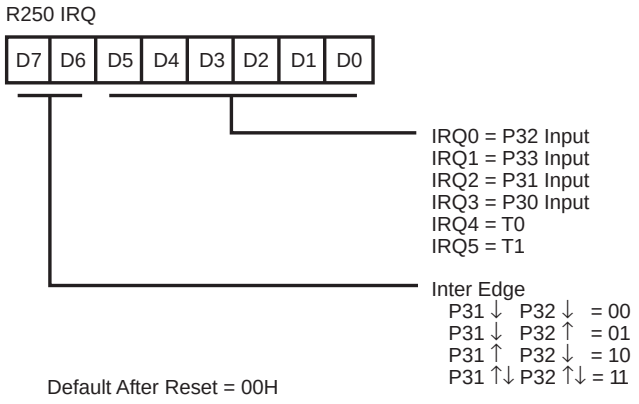
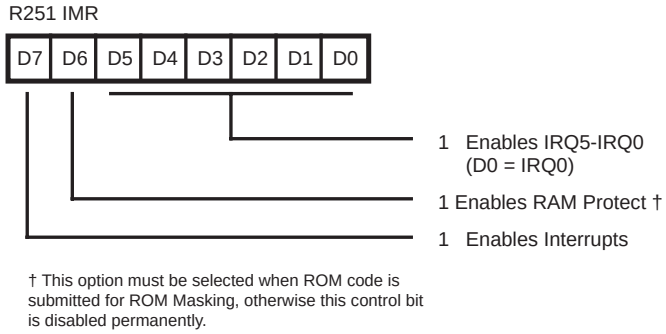


Figure 55. Interrupt Request Register
FAH: Read/Write



† This option must be selected when ROM code is submitted for ROM Masking, otherwise this control bit is disabled permanently.

Figure 56. Interrupt Mask Register
FBH: Read/Write

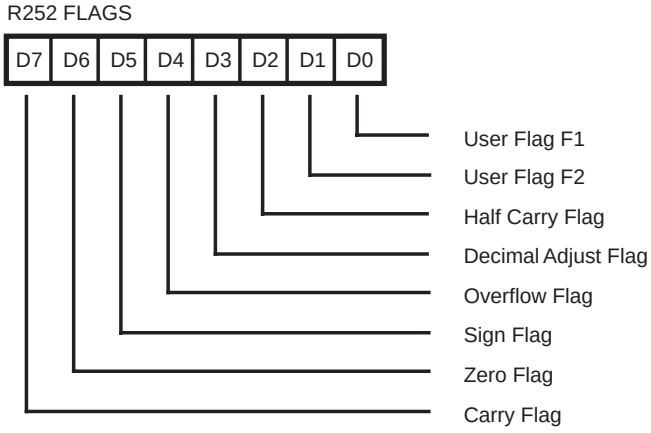


Figure 57. Flag Register
FCH: Read/Write

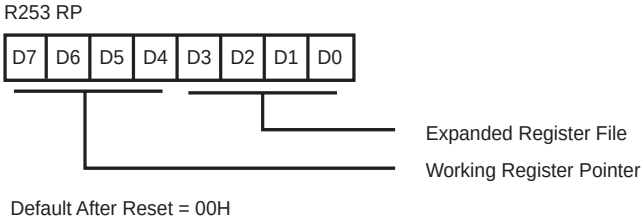


Figure 58. Register Pointer
FDH: Read/Write

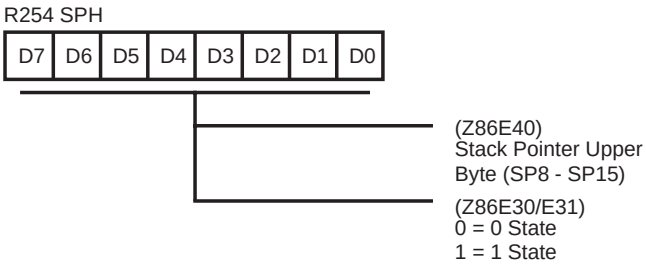


Figure 59. Stack Pointer High
FEH: Read/Write

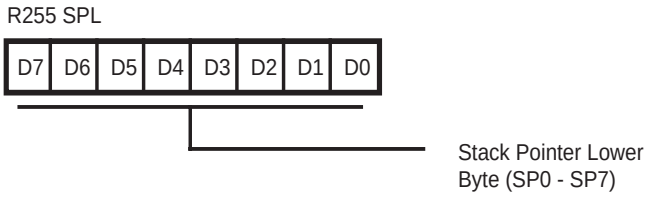
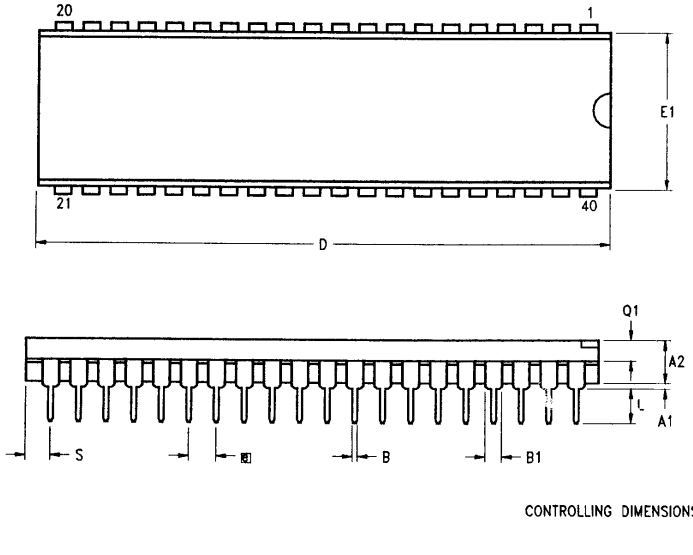


Figure 60. Stack Pointer Low
FFH: Read/Write

PACKAGE INFORMATION (Continued)

PACKAGE INFORMATION



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.51	1.02	.020	.040
A2	3.18	3.94	.125	.155
B	0.38	0.53	.015	.021
B1	1.02	1.52	.040	.060
C	0.23	0.38	.009	.015
D	52.07	52.58	2.050	2.070
E	15.24	15.75	.600	.620
E1	13.59	14.22	.535	.560
e	2.54 TYP		.100 TYP	
eA	15.49	16.76	.610	.660
L	3.05	3.81	.120	.150
Q1	1.52	1.91	.060	.075
S	1.52	2.29	.060	.090

Figure 61. 40-Pin DIP Package Diagram

ORDERING INFORMATION

Z86E40 (16 MHz)

40-Pin DIP	44-Pin PLCC	44-Pin LQFP
Z86E4016PSC	Z86E4016VSC	Z86E4016FSC
Z86E4016PEC	Z86E4016VEC	Z86E4016FEC

Z86E30 (16 MHz)

28-Pin DIP	28-Pin SOIC	28-Pin PLCC
Z86E3016PSC	Z86E3016SSC	Z86E3016VSC
Z96E3016PEC	Z86E3016SEC	Z86E3016VEC

Z86E31 (16 MHz)

28-Pin DIP	28-Pin SOIC	28-Pin PLCC
Z86E3116PSC	Z86E3116SSC	Z86E3116VSC
Z86E3116PEC	Z86E3116SEC	Z86E3116VEC

For fast results, contact your local Zilog sales office for assistance in ordering the part desired.

Package

P = Plastic DIP

V = Plastic Leaded Chip Carrier

F = Plastic Quad Flat Pack

S = SOIC (Small Outline Integrated Circuit)

Temperature

S = 0 °C to +70 °C
E = -40 °C to +105 °C

Speed

16 = 16 MHz

Environmental

C= Plastic Standard

E = Hermetic Standard

Example:

Z 86E40 16 P S C is a Z86E40, 16 MHz, DIP, 0°C to +70°C, Plastic Standard Flow